



National Standards Authority of Ireland

IRISH STANDARD

I.S. EN 60191-6-3:2001

ICS 31.080.01

**MECHANICAL STANDARDIZATION OF
SEMICONDUCTOR DEVICES
PART 6-3: GENERAL RULES FOR THE
PREPARATION OF OUTLINE DRAWINGS OF
SURFACE MOUNTED SEMICONDUCTOR
DEVICE PACKAGES - MEASURING
METHODS FOR PACKAGE DIMENSIONS OF
QUID FLAT PACKS (QFP)
(IEC 60191-6-3:2000)**

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*This Irish Standard was
published under the
authority of the National
Standards Authority of
Ireland
and comes into effect on
June 22, 2001*

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EUROPEAN STANDARD

EN 60191-6-3

NORME EUROPÉENNE

EUROPÄISCHE NORM

December 2000

ICS 31 080 01

English version

Mechanical standardization of semiconductor devices
Part 6-3: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages -
Measuring methods for package dimensions of quad flat packs (QFP)
(IEC 60191-6-3:2000)

Normalisation mécanique des dispositifs
à semiconducteurs
Partie 6-3 : Règles générales pour
la préparation des dessins
d'encombrement des dispositifs à
semiconducteurs à montage en surface -
Méthodes de mesure pour les boîtiers
plats quadrangulaires (QFP)
(CEI 60191-6-3:2000)

Mechanische Normung von
Halbleiterbauelemente
Teil 6-3: Allgemeine Regeln für die
Erstellung von Gehäusezeichnungen
von SMD-Halbleitegehäusen -
Meßverfahren für QFP-Gehäusemaße
(IEC 60191-6-3:2000)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/370/FDIS, future edition 1 of IEC 60191-6-3, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-3 on 2000-11-01

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2001-08-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2003-11-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-3:2000 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-6	1990	Mechanical standardization of semiconductor devices Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	-	-

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